LITE ON SEMICONDUCTOR

Customer Notification of Product/Process Changes

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*PCN No.: P16028	*Issued Date: Nov/14/2016 *Effective date: Feb/10/2017	
*Subject: Change clip joint method		
*Affected category: F3-D	*Affected family: GPP.SCH	

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Change Item	☐ Material ■ Design ☐ Process	☐ Others
Impact Item	1. Product P/N □ Yes III No	3. Label : ☐ Yes 🍱 No
	2. Marking : ☐ Yes ■ No	4. Other items : ☐ Yes ■ No
Other Related Item	N/A	
Change Purpose	Change clip joint method to improve the soldering yield	
	Before Change	After Change
Description of Change	Flat joint method	Card slot joint method
Relevant	☐ Electrical Test Report (as the attachment)	
Verification Report	☐ Mechanical Test Report (as the attachment) ☐Others (ex. Impacted part list) :(as the attachment)	
	Others (ex. impacted part list) (as	the attachment)
Other Related Report	<u>N/A</u>	
Sample availability	¥Yes ⊡No	•
Customer	Approve	
Approval	☐ Disapprove	
Customer Requirement (ex. Last Buy requirement)		

Note:

- (1.) If you need sample(s) or any question, please contact with our Salesperson within 30day
- (2.) PCN for customer notification/response, ref. JEDEC No. 46 sec 3.2.3 to implement.

Quality Assurance